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APPLICATION NO.	FI	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
09/912,064	C	07/25/2001	Takahiro Oka	TAI 129	TAI 129 3312	
23995	7590	12/20/2004		EXAM	EXAMINER	
RABIN &			ERDEM, FAZLI			
1101 14TH SUITE 500	STREET, 1	NW		ART UNIT	PAPER NUMBER	
WASHINGTON, DC 20005				2826		

DATE MAILED: 12/20/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application No.	Applicant(s)	
Office Action Summary		09/912,064	OKA ET AL.	
		Examiner	Art Unit	
		Fazli Erdem	2826	
The MAI Period for Reply	LING DATE of this communication ap	pears on the cover sheet with the	correspondence addre	ss
A SHORTENED THE MAILING I - Extensions of time after SIX (6) MONT - If the period for repl - If NO period for repl - Failure to reply with Any reply received earned patent term	O STATUTORY PERIOD FOR REPL DATE OF THIS COMMUNICATION. may be available under the provisions of 37 CFR 1. HS from the mailing date of this communication. y specified above is less than thirty (30) days, a reply is specified above, the maximum statutory period in the set or extended period for reply will, by statut by the Office later than three months after the mailing adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply be ti oly within the statutory minimum of thirty (30) da will apply and will expire SIX (6) MONTHS fror e, cause the application to become ABANDON	imely filed ys will be considered timely. n the mailing date of this comm ED (35 U.S.C. § 133).	unication.
Status	•			
2a)⊠ This action 3)□ Since this	ve to communication(s) filed on 23 sometimes application is in condition for allowated accordance with the practice under	s action is non-final. ance except for formal matters, pi		erits is
Disposition of Cla	ms			
4a) Of the 5)	1 and 3-20 is/are pending in the app above claim(s) is/are withdra 3,6,8,10,12-16 and 19 is/are allowed 1,4,9,11,17,18 and 20 is/are rejected 5 and 7 is/are objected to are subject to restriction and/o	awn from consideration. l. d.		
Application Paper	5			
10)☐ The drawi Applicant r Replacem	fication is objected to by the Examining(s) filed on is/are: a) across any not request that any objection to the ent drawing sheet(s) including the corrector declaration is objected to by the E	cepted or b) objected to by the drawing(s) be held in abeyance. Setion is required if the drawing(s) is o	ee 37 CFR 1.85(a). bjected to. See 37 CFR ²	• •
Priority under 35 l	J.S.C. § 119			
a) All b) 1. Cer 2. Cer 3. Cor app	dgment is made of a claim for foreign Some * c) None of: tified copies of the priority document tified copies of the priority document oies of the certified copies of the priority document tified copies of the priority document oies of the certified copies of the priority document of the priority docu	nts have been received. Its have been received in Applica Drity documents have been receiven Drity (PCT Rule 17.2(a)).	tion No ved in this National Sta	age
Attachment(s) 1) X Notice of Reference	ces Cited (PTO-892)	4) ☐ Interview Summar	v (PTO-413)	
2) 🔲 Notice of Draftspe	rson's Patent Drawing Review (PTO-948) sure Statement(s) (PTO-1449 or PTO/SB/08	Paper No(s)/Mail D		i2)

Allowable Subject Matter

1. Claims 3, 6, 8, 10, 12-16 and 19 allowed.

The following is a statement of reasons for the indication of allowable subject matter:

Prior art failed to establish semiconductor chip package with the adhesive sheet in the required manner.

2. Claims 5 and 7 objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The following is a statement of reasons for the indication of allowable subject matter:

Prior art failed to establish the required sunken region on the substrate.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 1,4, 9, 11, 17, 18 and 20 rejected under 35 U.S.C. 103(a) as being unpatentable over Tzu (6,201,302) in view of Kim et al. (KR 2002042958) further in view of Rolda, Jr. et al. (2002/0030261).

Regarding Claims 1,4, 9, 11, 17, 18 and 20, Tzu discloses semiconductor package having multi-dies where in Fig. 3, semiconductor dies 306 and 312 are mounted on the substrate 302 with wiring 310 connecting the semiconductor dies to the substrate. As the

figure shows the semiconductor substrate 302 has an opening larger than the lower die 312 but smaller than the upper die 306. Tzu fails to disclose the required insulating reverse side mounting of the upper and the lower semiconductor ships and the interposer between the two dies. However, Kim et al. disclose stacked chip package where chip 32 is mounted on chip 42 in a reverse manner that is the non-electrode sides are facing each other. Furthermore, Rolda, Jr. et al. disclose a multi-flip-chip semiconductor assembly where in Fig 1, the element 12 that is between the semiconductor chips 110 and 130 is an insulating interposer.

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It would have been obvious to one of having ordinary skill in the art at the time the invention was made to include the required reverse manner stacking of upper and lower semiconductor chips and insulating interposer between the upper and the lower semiconductor dies in Tzu as taught by Kim et al. and Rolda, Jr. et al. respectively, in order to have a semiconductor packaging structure with higher reliability.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37

Art Unit: 2826

CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Fazli Erdem whose telephone number is (571) 272-1914. The examiner can normally be reached on M - F 8:00 - 5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272-1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

FE December 11, 2004

NATHAN J. FLYNN SUPERVISORY PATENT EXAMINER TECHNOLOGY PENTER 2800